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ANNOUNCEMENTS

10th European Conference on Thermophysical Properties
Rome, Italy
September 22–26, 1986

The 10th European Conference on Thermophysical Properties will be held at the University of Rome from September 22 to 26, 1986.

The conference will concentrate on the following properties and techniques involved in their measurement: heat capacity, temperature and heat of transition, thermal expansion, thermal conductivity and diffusivity, electric conductivity, and emissivity, with emphasis on condensed phase above room temperature. Outside this range only papers of particular relevance will be accepted.

Consideration will be given to the following materials: chemical elements and compounds, alloys, ceramics, composite materials, and geological materials. Papers on materials for use in energy production and conservation will be especially welcome.

Contributions will be presented orally and as posters.

Chairman of the Conference is Professor G. Ruffino.

For further information please contact:

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9th International Thermal Expansion Symposium
Pittsburgh, Pennsylvania, U.S.A.
December 8–10, 1986

The conference is a well established event for those actively involved with, or interested in thermophysical behavior of materials, and methods/equipment used in their measurement. The meeting provides a forum for presentation of findings related to research activities as well as to industrial applications. Some of the topics to be discussed will be:

- Thermal expansion of geological materials and problems related to nuclear waste disposal site work.
- Nuclear applications, power plant and reactor components.
- Composite materials and the quest for tailoring expansion behavior to needs.
- Plastics and other nonmetallic systems. Application oriented testing.
- Testing methodology for unconventional shapes and applications (foil, yarn, woven fabric, thin plate, sandwiched laminates, molded bodies, etc.). Applicability of dilatometry in sintering studies.
- Automotive and transportation oriented materials development.
- High speed and high accuracy methods for advanced research.
- New fields of interest, such as electronic materials, circuit boards, and integrated circuit chip packaging.
- Thermal expansion testing as a Quality Control tool.

Papers are also solicited for presentation in all related areas. In addition, invited papers by eminent experts in certain key fields will be given. Participation of those new to the field are encouraged with the inclusion of a Workshop on Laboratory Techniques and an exhibit of testing equipment as part of the symposium.

For further information please contact:

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